



# SMAJ SERIES

## 400 Watts Surface Mount Transient Voltage Suppressor

### SMA/DO-214AC

### Features

- ✧ For surface mounted application
- ✧ Low profile package
- ✧ Built-in strain relief
- ✧ Glass passivated junction
- ✧ Excellent clamping capability
- ✧ Fast response time: Typically less than 1.0ps from 0 volt to BV min.
- ✧ Typical  $I_R$  less than  $1\mu A$  above 10V
- ✧ High temperature soldering guaranteed:  $260^{\circ}C$  / 10 seconds at terminals
- ✧ Plastic material used carries Underwriters Laboratory Flammability Classification 94V-0
- ✧ 400 watts peak pulse power capability with a 10 x 1000 us waveform (300W above 78V).
- ✧ Green compound with suffix "G" on packing code & prefix "G" on datecode.

### Mechanical Data

- ✧ Case: Molded plastic
- ✧ Terminals: Pure tin plated lead free,
- ✧ Polarity: Indicated by cathode band
- ✧ Standard packaging: 12mm tape (EIA STD RS-481)
- ✧ Weight: 0.064 gram

### Maximum Ratings and Electrical Characteristics

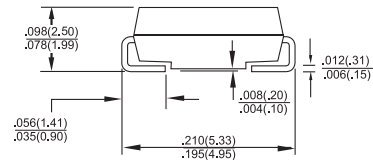
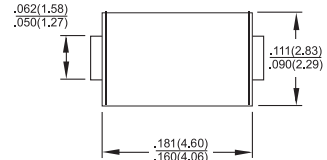
Rating at  $25^{\circ}C$  ambient temperature unless otherwise specified.

Type Number	Symbol	Value	Units
Peak Power Dissipation at $T_A=25^{\circ}C$ , $T_p=1ms$ (Note 1)	PK	Minimum 400	Watts
Steady State Power Dissipation	$P_d$	1	Watts
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method) (Note 2, 3)	$I_{FSM}$	40.0	Amps
Maximum Instantaneous Forward Voltage at 25.0A for Unidirectional Only	$V_F$	3.5	Volts
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to + 150	$^{\circ}C$

- Notes:
1. Non-repetitive Current Pulse Per Fig. 3 and Derated above  $T_A=25^{\circ}C$  Per Fig. 2.
  2. Mounted on  $10mm^2$  (.035 mm Thick) Copper Pads to Each Terminal.
  3. 8.3ms Single Half Sine-wave or Equivalent Square Wave, Duty Cycle=4 Pulses Per Minute Maximum.

#### Devices for Bipolar Applications

1. For Bidirectional Use C or CA Suffix for Types SMAJ5.0 through Types SMAJ188.
2. Electrical Characteristics Apply in Both Directions.



Dimensions in inches and (millimeters)

#### Marking Diagram



- XX = Specific Device Code
- G = Green Compound
- Y = Year
- M = Work Month

## RATINGS AND CHARACTERISTIC CURVES (SMAJ SERIES)

FIG.1- PEAK PULSE POWER RATING CURVE

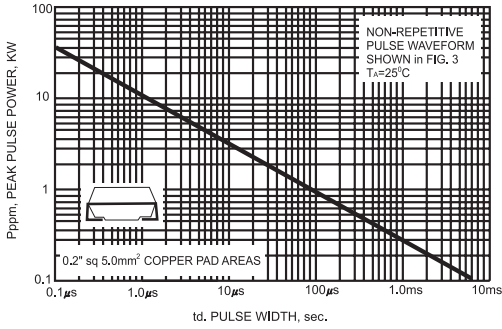


FIG.2- PULSE DERATING CURVE

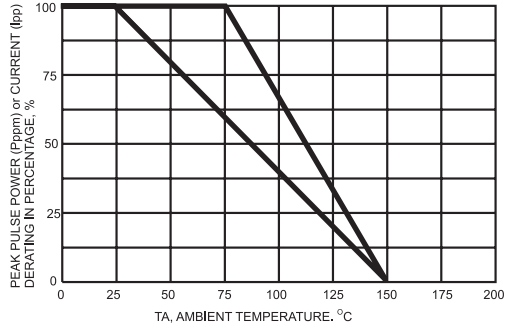


FIG.3- CLAMPING POWER PULSE WAVEFORM

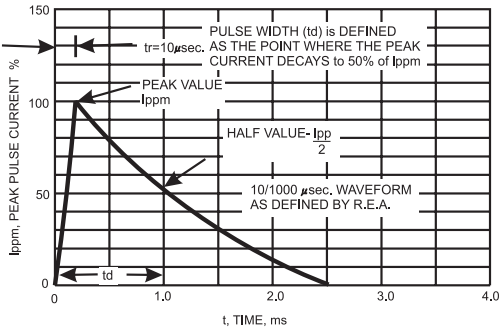


FIG.4- MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

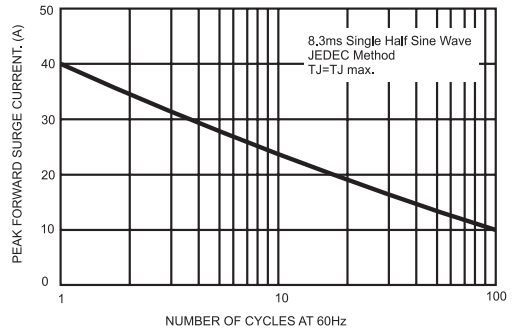
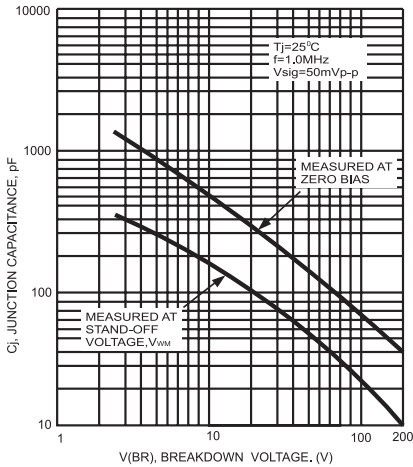


FIG.5- TYPICAL JUNCTION CAPACITANCE



## ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

Device	Device Marking Code	Working Peak Reverse Voltage V <sub>wm</sub> (Volts)	Breakdown Voltage V <sub>(BR)</sub> (Volts) at I <sub>r</sub>		Test Current I <sub>r</sub> (mA)	Maximum Clamping Voltage at I <sub>PPM</sub> V <sub>c</sub> (Volts) (Note 5)	Maximum Peak Pulse Surge Current I <sub>PPM</sub> (Note 5)(Amps)	Maximum Reverse Leakage at V <sub>wm</sub> I <sub>o</sub> (uA)
			Min.	Max.				
SMAJ5,0	AD	5,0	6,40	7,30	10	9,6	41,7	800
SMAJ5,0A	AE	5,0	6,40	7,00	10	9,2	43,5	800
SMAJ6,0	AF	6,0	6,67	8,15	10	11,4	35,1	800
SMAJ6,0A	AG	6,0	6,67	7,37	10	10,3	38,8	800
SMAJ6,5	AH	6,5	7,22	8,82	10	12,3	32,5	500
SMAJ6,5A	AK	6,5	7,22	7,98	10	11,2	35,7	500
SMAJ7,0	AL	7,0	7,78	9,51	10	13,3	30,1	200
SMAJ7,0A	AM	7,0	7,78	8,60	10	12,0	33,3	200
SMAJ7,5	AN	7,5	8,33	10,30	1,0	14,3	28,0	100
SMAJ7,5A	AP	7,5	8,33	9,21	1,0	12,9	31,0	100
SMAJ8,0	AQ	8,0	8,89	10,9	1,0	15,0	26,7	50,0
SMAJ8,0A	AR	8,0	8,89	9,83	1,0	13,6	29,4	50,0
SMAJ8,5	AS	8,5	9,44	11,5	1,0	15,9	25,2	10,0
SMAJ8,5A	AT	8,5	9,44	10,4	1,0	14,4	27,8	10,0
SMAJ9,0	AU	9,0	10,0	12,2	1,0	16,9	23,7	5,0
SMAJ9,0A	AV	9,0	10,0	11,1	1,0	15,4	26,0	5,0
SMAJ10	AW	10	11,1	13,6	1,0	18,8	21,3	5,0
SMAJ10A	AX	10	11,1	12,3	1,0	17,0	23,5	5,0
SMAJ11	AY	11	12,2	14,9	1,0	20,1	19,9	5,0
SMAJ11A	AZ	11	12,2	13,5	1,0	18,2	22,0	5,0
SMAJ12	BD	12	13,3	16,3	1,0	22,0	18,2	5,0
SMAJ12A	BE	12	13,3	14,7	1,0	19,9	20,1	5,0
SMAJ13	BF	13	14,4	17,6	1,0	23,8	16,8	5,0
SMAJ13A	BG	13	14,4	15,9	1,0	21,5	18,6	5,0
SMAJ14	BH	14	15,6	19,1	1,0	25,8	15,5	5,0
SMAJ14A	BK	14	15,6	17,2	1,0	23,2	17,2	5,0
SMAJ15	BL	15	16,7	20,4	1,0	26,9	14,9	5,0
SMAJ15A	BM	15	16,7	18,5	1,0	24,4	16,4	5,0
SMAJ16	BN	16	17,8	21,8	1,0	28,8	13,9	5,0
SMAJ16A	BP	16	17,8	19,7	1,0	26,0	15,4	5,0
SMAJ17	BQ	17	18,9	23,1	1,0	30,5	13,1	5,0
SMAJ17A	BR	17	18,9	20,9	1,0	27,6	14,5	5,0
SMAJ18	BS	18	20,0	24,4	1,0	32,2	12,4	5,0
SMAJ18A	BT	18	20,0	22,1	1,0	29,2	13,7	5,0
SMAJ20	BU	20	22,2	27,1	1,0	35,8	11,2	5,0
SMAJ20A	BV	20	22,2	24,5	1,0	32,4	12,3	5,0
SMAJ22	BW	22	24,4	29,8	1,0	39,4	10,2	5,0
SMAJ22A	BX	22	24,4	26,9	1,0	35,5	11,3	5,0
SMAJ24	BY	24	26,7	32,6	1,0	43,0	9,3	5,0
SMAJ24A	BZ	24	26,7	29,5	1,0	38,9	10,3	5,0
SMAJ26	CD	26	28,9	35,3	1,0	46,6	8,6	5,0
SMAJ26A	CE	26	28,9	31,9	1,0	42,1	9,5	5,0
SMAJ28	CF	28	31,1	38,0	1,0	50,0	8,0	5,0
SMAJ28A	CG	28	31,1	34,4	1,0	45,4	8,8	5,0
SMAJ30	CH	30	33,3	40,7	1,0	53,5	7,5	5,0
SMAJ30A	CK	30	33,3	36,8	1,0	48,4	8,3	5,0
SMAJ33	CL	33	36,7	44,9	1,0	59,0	6,8	5,0
SMAJ33A	CM	33	36,7	40,6	1,0	53,3	7,5	5,0
SMAJ36	CN	36	40,0	48,9	1,0	64,3	6,2	5,0
SMAJ36A	CP	36	40,0	44,2	1,0	58,1	6,9	5,0
SMAJ40	CQ	40	44,4	54,3	1,0	71,4	5,6	5,0
SMAJ40A	CR	40	44,4	49,1	1,0	64,5	6,2	5,0
SMAJ43	CS	43	47,8	58,4	1,0	76,7	5,2	5,0
SMAJ43A	CT	43	47,8	52,8	1,0	69,4	5,8	5,0

ELECTRICAL CHARACTERISTICS (TA=25°C unless otherwise noted)

Device	Device Marking Code	Working Peak Reverse Voltage V <sub>WRM</sub> (Volts)	Breakdown Voltage V <sub>(BR)</sub> (Volts) at I <sub>r</sub>		Test Current I <sub>r</sub> (mA)	Maximum Clamping Voltage at I <sub>PPM</sub> V <sub>c</sub> (Volts) (Note 5)	Maximum Peak Pulse Surge Current I <sub>PPM</sub> (Amps) (Note 5)	Maximum Reverse Leakage at V <sub>WRM</sub> I <sub>o</sub> (uA)
			Min.	Max.				
SMAJ45	CU	45	50.0	61.1	1.0	80.3	5.0	5.0
SMAJ45A	CV	45	50.0	55.3	1.0	72.7	5.5	5.0
SMAJ48	CW	48	53.3	65.1	1.0	85.5	4.7	5.0
SMAJ48A	CX	48	53.3	58.9	1.0	77.4	5.2	5.0
SMAJ51	CY	51	56.7	69.3	1.0	91.1	4.4	5.0
SMAJ51A	CZ	51	56.7	62.7	1.0	82.4	4.9	5.0
SMAJ54	RD	54	60.0	73.3	1.0	96.3	4.2	5.0
SMAJ54A	RE	54	60.0	66.3	1.0	87.1	4.6	5.0
SMAJ58	RF	58	64.4	78.7	1.0	103	3.9	5.0
SMAJ58A	RG	58	64.4	71.2	1.0	93.6	4.3	5.0
SMAJ60	RH	60	66.7	81.5	1.0	107	3.7	5.0
SMAJ60A	RK	60	66.7	73.7	1.0	96.8	4.1	5.0
SMAJ64	RL	64	71.1	86.9	1.0	114	3.5	5.0
SMAJ64A	RM	64	71.1	78.6	1.0	103	3.9	5.0
SMAJ70	RN	70	77.8	95.1	1.0	125	3.2	5.0
SMAJ70A	RP	70	77.8	86.0	1.0	113	3.5	5.0
SMAJ75	RQ	75	83.3	102	1.0	134	3.0	5.0
SMAJ75A	RR	75	83.3	92.1	1.0	121	3.3	5.0
SMAJ78	RS	78	86.7	106	1.0	139	2.9	5.0
SMAJ78A	RT	78	86.7	95.8	1.0	126	3.2	5.0
SMAJ85	RU	85	94.4	115	1.0	151	2.0	5.0
SMAJ85A	RV	85	94.4	104	1.0	137	2.2	5.0
SMAJ90	RW	90	100	122	1.0	160	1.9	5.0
SMAJ90A	RX	90	100	111	1.0	146	2.1	5.0
SMAJ100	RY	100	111	136	1.0	179	1.7	5.0
SMAJ100A	RZ	100	111	123	1.0	162	1.9	5.0
SMAJ110	SD	110	122	149	1.0	196	1.6	5.0
SMAJ110A	SE	110	122	135	1.0	177	1.7	5.0
SMAJ120	SF	120	133	163	1.0	214	1.4	5.0
SMAJ120A	SG	120	133	147	1.0	193	1.6	5.0
SMAJ130	SH	130	144	176	1.0	231	1.3	5.0
SMAJ130A	SK	130	144	159	1.0	209	1.5	5.0
SMAJ150	SL	150	167	204	1.0	266	1.1	5.0
SMAJ150A	SM	150	167	185	1.0	243	1.3	5.0
SMAJ160	SN	160	178	218	1.0	287	1.0	5.0
SMAJ160A	SP	160	178	197	1.0	259	1.2	5.0
SMAJ170	SQ	170	189	231	1.0	304	1.0	5.0
SMAJ170A	SR	170	189	209	1.0	275	1.1	5.0
SMAJ188	ST	188	209	255	1.0	344	0.9	5.0
SMAJ188A	SS	188	209	231	1.0	328	0.91	5.0

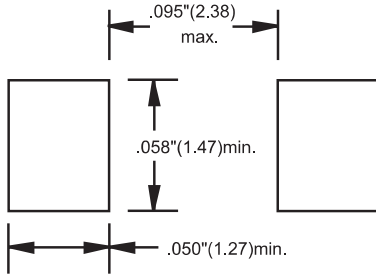
Notes:

1. Non-repetitive current pulse, per Fig. 3 and derated above TA=25°C per Fig. 2
2. Mounted on 5.0mm<sup>2</sup> copper pads to each terminal
3. Lead temperature at TL=75°C
4. Measured on 8.3ms single half sine-wave duty cycle=4 pulses per minutes maximum
5. Peak pulse power waveform is 10/1000 us
6. For Bi-Directional devices having VR of 10 volts and under, the IR limit is double.

# APPLICATION NOTES:

## Recommended Pad Layout

The pad dimensions should be 0.010" longer than the contact size in the lead axis. This allows a solder fillet to form, see figure below. Contact factory for soldering methods.



Dimensions in inches and (millimeters)

This device is designed specifically for transient voltage suppression from threats generated by ESD for board level load switching components.

The wide leads assure a large surface contact for good heat dissipation, and a low resistance path for surge current flow to ground.

This series is designed to optimize board space and for use with surface mount technology automated assembly equipment.

They can be easily mounted on printed circuit boards and ceramic substrates to protect sensitive components from transient voltage damage.